



Xilinx Package Drawings

NO	Package Drawing	Decal Name	Remark	date	Owner
1	320-Ball Fine-Pitch BGA(FG320/FGG320) Package	FBGA320-1M-19X19	sr18: surface round 18mil	2004-07-26	Dai Wei-na
2	48-Pin TSOP, 0.50mm Pitch (VO48/VOG48) Package	TSOP48-0.5M-18.5X12	sl75X12: surface rectangle 75x12	2004-07-26	Dai Wei-na
3	BF560: Plastic Flip-Chip BGA Package	BGA560-50-1674X1674	sr20: surface round 20mil	2004-07-26	Dai Wei-na
4	Plastic Flip-Chip BGA (BF957) Package	BGA957-50-1574X1574	sr20: surface round 20mil	2004-07-26	Dai Wei-na
5	Plastic BGA (BG225) Package	BGA225-1.5M-27X27	sr20: surface round 20mil	2004-07-26	Dai Wei-na
6	Plastic BGA (BG256) Package	BGA256-50-1064X1064	sr20: surface round 20mil	2004-07-27	Dai Wei-na
7	Metal BGA (BG352) — Cavity Down Package	HBGA352-50-1378X1378	sr18: surface round 18mil sq750: surface square 750mil	2004-07-27	Dai Wei-na
8	Plastic BGA (BG388) Package	BGA388-50-1378X1378	sr20: surface round 20mil	2004-07-27	Dai Wei-na
9	Metal BGA (BG432) — Cavity Down Package	HBGA432-50-1576X1576	sr18: surface round 18mil sq750: surface square 750mil	2004-07-27	Dai Wei-na
10	Plastic BGA (BG492) Package	BGA492-50-1378X1378	sr20: surface round 20mil	2004-07-27	Dai Wei-na
11	Metal BGA (BG560) Package	HBGA560-50-1674X1674	sr18: surface round 18mil sq1000: surface square 1000mil	2004-07-27	Dai Wei-na
12	Plastic BGA (BG728) Package	BGA728-50-1378X1378	sr20: surface round 20mil	2004-07-28	Dai Wei-na
13	CB100-Ceramic Braized CQFP	CB100-25-750X750-LU CB100-25-750X750-LD	sl60X12: surface rectangle 60x12 sl60X12: surface rectangle 60x12	2004-07-29	Dai Wei-na
14	CB164-Ceramic Braized CQFP	CB164-25-1150X1150-LU CB164-25-1150X1150-LD	sl60X12: surface rectangle 60x12 sl60X12: surface rectangle 60x12	2004-07-29	Dai Wei-na
15	CB196-Ceramic Braized CQFP	CB196-25-1350X1350-LU CB196-25-1350X1350-LD	sl60X12: surface rectangle 60x12 sl60X12: surface rectangle 60x12	2004-07-29	Dai Wei-na
16	CB228-Ceramic Braized CQFP	CB228-25-1550X1550-LU CB228-25-1550X1550-LD	sl60X12: surface rectangle 60x12 sl60X12: surface rectangle 60x12	2004-07-29	Dai Wei-na
17	CC20-Ceramic Quad	CC20-50-380X380	sl28X80: surface rectangle 28x80	2004-07-29	Dai Wei-na
18	CC44: Ceramic Chip Carrier Package	CC44-50-665X665	sl80X28: surface rectangle 80x28	2004-07-30	Dai Wei-na
19	Ceramic BGA (CG1156) Package	BGA1156-1M-35X35	sr18: surface round 18mil	2004-07-30	Dai Wei-na

20	CG560: Ceramic Column Grid Array Package	CHBGA560-50-1674X1674	sr24: surface round 24mil	2004-08-2	Dai Wei-na
			sq1000: surface square 1000mil		
21	Chip Scale BGA (CP132/CPG132) Package	BGA132-0_5M-8X8	sr0_3m: surface round 0.3mm	2004-08-2	Dai Wei-na
22	Chip Scale BGA (CP56/CPG56) Package	BGA56-0_5M-6X6	sr0_3m: surface round 0.3mm		
23	Chip Scale BGA (CS144/CSG144) Package	BGA144-0_8M-12X12	sr14: surface round 14mil	2004-08-2	Dai Wei-na
			sr14-ns: surface round 14mil,no solder pad		
24	Chip Scale BGA (CS280/CSG280) Package	BGA280-0_8M-16X16	sr14: surface round 14mil	2004-08-2	Dai Wei-na
			sr14-ns: surface round 14mil,no solder pad		
25	Chip Scale BGA (CS48/CSG48) Package	BGA48-0_8M-7X7	sr14: surface round 14mil	2004-08-2	Dai Wei-na
26	Chip Scale BGA (FS48) Package	BGA48-0_8M-8X9	sr14: surface round 14mil	2004-08-2	Dai Wei-na
27	Ceramic DIP (DD8) Package	DIP8-100-310X430	ts:through hole,hole round39,pad square 5	2004-08-9	Dai Wei-na
			tr:through hole,hole round39,pad round 59		
28	FF1148: Plastic Flip-Chip BGA Package	BGA1148-1M-35X35	sr18: surface round 18mil	2004-08-9	Dai Wei-na
29	Flip Chip BGA (FF1152) Package	BGA1152-1M-35X35	sr18: surface round 18mil	2004-08-10	Dai Wei-na
30	Flip Chip BGA (FF1517) Package	BGA1517-1M-40X40	sr18: surface round 18mil	2004-08-10	Dai Wei-na
31	FF1696: Plastic Flip-Chip BGA Package	BGA1696-1M-42_5X42_5	sr18: surface round 18mil	2004-08-10	Dai Wei-na
32	FF1704: Plastic Flip-Chip BGA Package	BGA1704-1M-42_5X42_5	sr18: surface round 18mil	2004-08-10	Dai Wei-na
33	FF672: Plastic Flip-Chip BGA Package	BGA672-1M-27X27	sr18: surface round 18mil	2004-08-10	Dai Wei-na
34	Flip Chip BGA (FF896) Package	BGA896-1M-31X31	sr18: surface round 18mil	2004-08-10	Dai Wei-na
35	Fine Pitch BGA (FG556) Package	BGA556-1M-31X31	sr18: surface round 18mil	2004-08-10	Dai Wei-na
36	Fine Pitch BGA (FG860) Package	BGA860-1M-42_5X42_5	sr18: surface round 18mil	2004-08-10	Dai Wei-na
37	Fine Pitch BGA (FG256/FGG256) Package	BGA256-1M-17X17	sr18: surface round 18mil	2004-08-10	Dai Wei-na
38	Fine Pitch BGA (FG324/FGG324) Package	BGA324-1M-23X23	sr18: surface round 18mil	2004-08-11	Dai Wei-na
39	Fine Pitch BGA (FG456/FGG456) Package	BGA456-1M-23X23	sr18: surface round 18mil	2004-08-11	Dai Wei-na
40	Fine Pitch BGA (FG676/FGG676) Package	BGA676-1M-27X27	sr18: surface round 18mil	2004-08-11	Dai Wei-na
41	Fine Pitch BGA (FG680/FGG680) Package	BGA680-1M-40X40	sr18: surface round 18mil	2004-08-11	Dai Wei-na
			sq1000: surface square 1000mil		
42	Fine Pitch Thin BGA (FT256/FTG256) Package	FBGA256-1M-17X17	sr14: surface round 14mil	2004-08-11	Dai Wei-na
43	Fine-Pitch BGA (FG1156/FGG1156) Package	FBGA1156-1M-35X35	sr14: surface round 14mil	2004-08-11	Dai Wei-na
44	Fine-Pitch BGA (FG900/FGG900) Package	BGA900-1M-31X31	sr14: surface round 14mil	2004-08-11	Dai Wei-na
45	Heat Sink PQFP (HQ160/HQG 160) Packages	HPQFP160-0_65M-28X28	sl75X15: surface rectangle 75x15mil	2004-07-28	Dai Wei-na
			sq750: surface square 750mil		

46	Heat Sink PQFP (HQ208/HQG 208) Packages	HPOFP208-0_5M-28X28	sl70X12: surface rectangle 70x12mil sq750: surface square 750mil	2004-07-28	Dai Wei-na
47	Heat Sink PQFP (HQ240/HQG 240) Packages	HPOFP240-0_5M-32X32	sl70X12: surface rectangle 70x12mil sq945: surface square 945mil	2004-07-26	Chen Li-ping
48	Heat Sink TQFP (HT100/HTG 100) Packages	HTOFP100-0_5M-14X14	sl70X12: surface rectangle 70x12mil sq395: surface square 395mil	2004-07-26	Chen Li-ping
49	Heat Sink TQFP (HT144/HTG 144) Packages	HTOFP144-0_5M-20X20	sl70X12: surface rectangle 70x12mil sq610: surface square 610mil	2004-07-26	Chen Li-ping
50	Heat Sink TQFP (HT176/HTG 176) Packages	HTOFP176-0_5M-24X24	sl70X12: surface rectangle 70x12mil sq765: surface square 765mil	2004-07-26	Chen Li-ping
51	HQ304-Heat Sink QFP	HPOFP304-0_5M-40X40	sl70X12: surface rectangle 70x12mil sq1220: surface square 1220mil	2004-07-27	Chen Li-ping
52	Molded BGA (BG575/BGG575) Package	BGA575-1_27M-31X31	sr24: surface round 24mil	2004-07-27	Chen Li-ping
53	PD08-Plastic DIP	DIP8-100-382X272	tr60h32: through round pad 60mil & hole 32m tq60h32: through square pad 60mil & hole 32m	2004-07-27	Chen Li-ping
54	PD48-Plastic DIP	DIP48-100-2480X580	tr60h32: through round pad 60mil & hole 32m tq60h32: through square pad 60mil & hole 32m	2004-07-27	Chen Li-ping
55	PG120-Ceramic PGA	PGA120-100-1360X1360	tr80h40: through round pad 80mil & hole 40m	2004-07-28	Chen Li-ping
56	PG132-Ceramic PGA	PGA132-100-1460X1460	tr80h40: through round pad 80mil & hole 40m	2004-07-28	Chen Li-ping
57	PG156-Ceramic PGA	PGA156-100-1660X1660	tr80h40: through round pad 80mil & hole 40m	2004-07-28	Chen Li-ping
58	PG175-Ceramic PGA	PGA175-100-1660X1660	tr80h40: through round pad 80mil & hole 40m	2004-07-28	Chen Li-ping
59	PG191-Ceramic PGA	PGA191-100-1860X1860	tr80h40: through round pad 80mil & hole 40m	2004-07-29	Chen Li-ping
60	PG223-Ceramic PGA	PGA223-100-1860X1860	tr80h40: through round pad 80mil & hole 40m	2004-07-29	Chen Li-ping
61	PG299-Ceramic PGA	PGA299-100-2060X2060	tr80h40: through round pad 80mil & hole 40m	2004-07-29	Chen Li-ping
62	PG411-Ceramic PGA	PGA411S-50-2060X2060	tr60h32: through round pad 60mil & hole 32m	2004-07-29	Chen Li-ping
63	PG475-Ceramic PGA	PGA475S-50-2160X2160	tr60h32: through round pad 60mil & hole 32m	2004-07-30	Chen Li-ping
64	PG559-Ceramic PGA	PGA559S-50-2260X2260	tr60h32: through round pad 60mil & hole 32m	2004-07-30	Chen Li-ping
65	PG68-Ceramic PGA	PGA68-100-1100X1100	tr60h32: through round pad 60mil & hole 32m	2004-07-30	Chen Li-ping
66	PG84-Ceramic PGA	PGA84-100-1100X1100	tr60h32: through round pad 60mil & hole 32m	2004-07-30	Chen Li-ping
67	PLCC (PC20/PCG 20) Packages	PLCC20-50-356X356	sl60X22: surface rectangle 60x22mil	2004-08-02	Chen Li-ping
68	PLCC (PC28/PCG 28) Packages	PLCC28-50-456X456	sl60X22: surface rectangle 60x22mil	2004-08-02	Chen Li-ping
69	PLCC (PC44/PCG 44) Packages	PLCC44-50-656X656	sl60X22: surface rectangle 60x22mil	2004-08-02	Chen Li-ping

70	PLCC (PC68/PCG 68) Packages	PLCC68-50-958X958	sl60X22: surface rectangle 60x22mil	2004-08-02	Chen Li-ping
71	PLCC (PC84/PCG 84) Packages	PLCC84-50-1158X1158	sl60X22: surface rectangle 60x22mil	2004-08-03	Chen Li-ping
72	PP132-Plastic PGA	PGA132-100-1460X1460	tr80h40: through round pad 80mil & hole 40m	2004-08-03	Chen Li-ping
73	PP175-Plastic PGA	PGA175-100-1660X1660	tr80h40: through round pad 80mil & hole 40m	2004-08-03	Chen Li-ping
74	PQ100-PQFP	PQFP100-0_65-20X14	sl80X16: surface rectangle 80x16mil	2004-08-03	Chen Li-ping
75	PQ304-PQFP	PQFP304-0_5M-40X40	sl70X12: surface rectangle 70x12mil	2004-08-04	Chen Li-ping
76	PQFP (PQ160/PQG 160) Packages	PQFP160-0_65M-28X28	sl80X16: surface rectangle 80x16mil	2004-08-04	Chen Li-ping
77	PQFP (PQ208/PQG 208) Packages	PQFP208-0_5M-28X28	sl70X12: surface rectangle 70x12mil	2004-08-04	Chen Li-ping
78	PQFP (PQ240/PQG 240) Packages	PQFP240-0_5M-32X32	sl70X12: surface rectangle 70x12mil	2004-08-04	Chen Li-ping
79	PQFP (PQ44/PQG 44) Packages	PQFP44-0_8M-10X10	sl80X18: surface rectangle 80x18mil	2004-08-05	Chen Li-ping
80	SO20-SOIC	SOIC20-50-505X296	sl85X20: surface rectangle 85x20mil	2004-08-05	Chen Li-ping
81	SO24-SOIC	SOIC24-50-605X296	sl85X20: surface rectangle 85x20mil	2004-08-05	Chen Li-ping
82	SO8-SOIC	SOIC8-20-194X155	sl75X20: surface rectangle 75x20mil	2004-08-05	Chen Li-ping
83	TQ128-TQFP	TQFP128-0_5M-14X20	sl70X12: surface rectangle 70x12mil	2004-08-06	Chen Li-ping
84	TQFP (TQ100/TQG 100) Packages	TQFP100-0_5M-14X14	sl70X12: surface rectangle 70x12mil	2004-08-06	Chen Li-ping
85	TQFP (TQ144/TQG 144) Packages	TQFP144-0_5M-20X20	sl70X12: surface rectangle 70x12mil	2004-08-06	Chen Li-ping
86	TQFP (TQ176/TQG 176) Packages	TQFP176-0_5M-24X24	sl70X12: surface rectangle 70x12mil	2004-08-06	Chen Li-ping
87	TSSOP (VO20/VOG20) Package	TSSOP20-25_6-256X173	sl78X12: surface rectangle 78x12mil	2004-08-10	Chen Li-ping
88	VO48-48-Pin TSOP, 0.50mm Pitch (VO48)	TSOP48-0_5M-18_5X12	sl75X12: surface rectangle 75x12mil	2004-08-10	Chen Li-ping
89	VO8-TSOP	TSOP8-50-194X155	sl75X20: surface rectangle 75x20mil	2004-08-10	Chen Li-ping
90	VQFP (VQ100/VQG 100) Package	VQFP100-0_5M-14X14	sl70X18: surface rectangle 70x18mil	2004-08-10	Chen Li-ping
91	VQFP (VQ44/VQG 44) Package	VQFP44-0_8M-10X10	sl70X12: surface rectangle 70x12mil	2004-08-10	Chen Li-ping
92	VQFP (VQ64/VQG 64) Package	VQFP64-0_5M-10X10	sl70X12: surface rectangle 70x12mil	2004-08-10	Chen Li-ping